RX Family

RX Driver Package Ver.1.16

R01AN4471EJ0116
Rev.1.16
Nov 20, 2018

Introduction

This document is the RX Family RX Driver Package User's Manual, version 1.16.

This User's Manual describes basic structures, features and usage of RX Driver Package applications, and about the sample application program using the FIT modules included in this package.

Note that older versions of the RX Driver Package can be obtained by clicking the "Sample Code" link after accessing the following URL.

RX Driver Package webpage: https://www.renesas.com/rdp

Target Devices

RX110, RX111, RX113, RX130 Group

RX210, RX230, RX231, RX23T, RX24T, RX24U Group

RX63N, RX64M, RX65N, RX651 Group, RX66T Group

RX71M Group

For Evaluation board, Renesas Starter Kit is used.

When using this application note with your product, careful evaluation is recommended.

And when using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Version of e² studio Used for Operation Confirmation

Operation of the RX Driver Package has been confirmed on e^2 studio V. 7.1.0.

The RX Driver Package can be obtained from within e^2 studio. Instructions are provided in section 4, Usage.

Related Documents

- RX Family Board Support Package Module Using Firmware Integration Technology (R01AN1685EJ)
- Firmware Integration Technology User's Manual (R01AN1833EU)
- RX Family Adding Firmware Integration Technology Modules to Projects (R01AN1723EU)
- RX Family Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826EJ)
- The User's Manual provided with the RX Driver Package Application.

Contents

1. Overview

1.1 Applicability

This User's Manual applies to the RX Family RX Driver Package, version 1.16. The System Build of this package is described below.

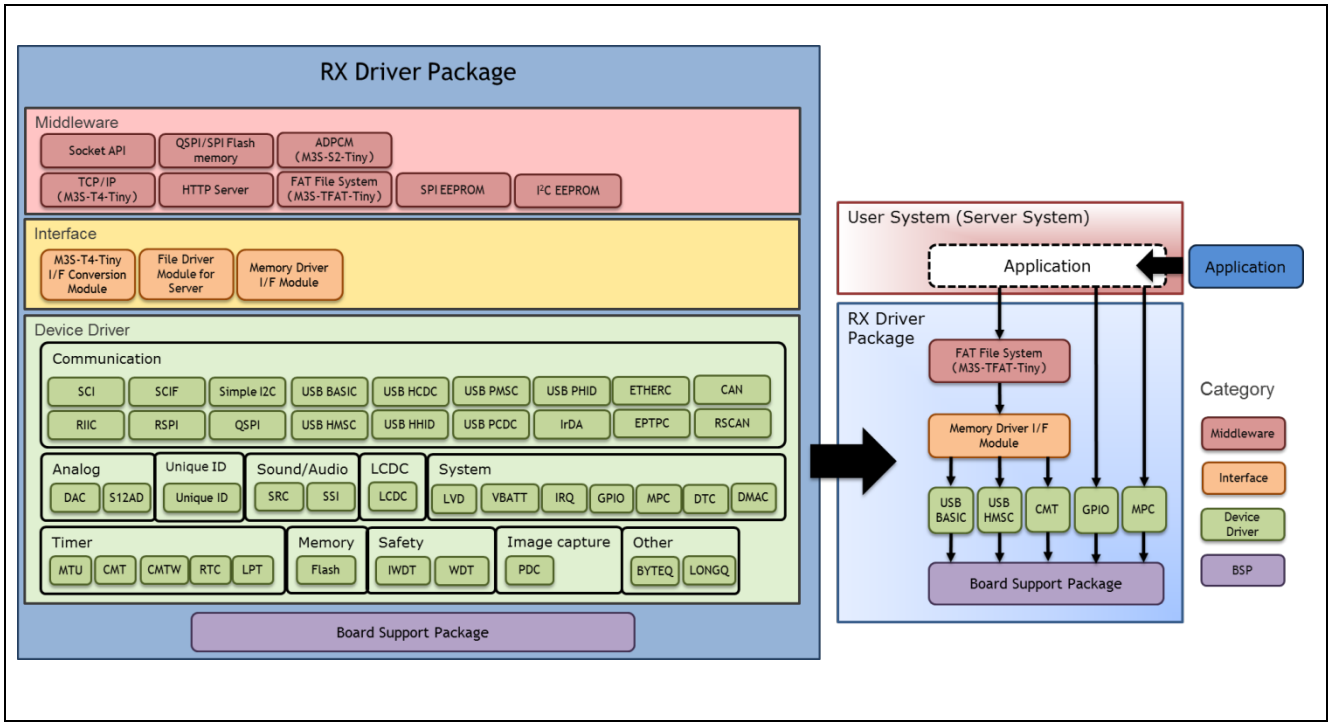

Figure 1-1 An Example of System Build

1.2 Operating Environment

This package runs under the operating environment described below.

Table 1-1 Operating Environment

Item	Contents
Integrated development environment	Renesas Electronics e^2 studio V7.1.0
C compiler	Renesas Electronics C/C++ compiler for RX Family V. 3.00.00
	Compiler options: The integrated development environment default settings are used, with the following option added. -lang = c99
Endian order	Big-endian/Little-endian
RDP version	Ver. 1.16
Board used	Renesas Starter Kit+ for RX64M (product No.: R0K50564Mxxxxxx) Renesas Starter Kit for RX231 (product No.: R0K505231xxxxxx) Renesas Starter Kit for RX130-512KB (product No.: RTK505130xxxxxxxxx) Renesas Starter Kit+ for RX65N-2MB (product No.: RTK50565Nxxxxxxxxx) Renesas Starter Kit for RX66T (product No.: RTK50566Txxxxxxxxx)

2. About RX Driver Package

The RX Driver Package is a software platform (framework) that combines the following modules to be required for development in a single package. Since the package contains multiple modules, you can start developing immediately without having to obtain each module separately.

Board Support Package (BSP) module

FIT peripheral function modules (free version)

FIT middleware modules (free version)

FIT interface modules

You can develop the user application layer with ease by using the Sample Application Program (RX Driver Package Application) which utilizes the RX Driver Package.

2.1 System Structure

The figure below shows the system structure of the RX Driver Package.

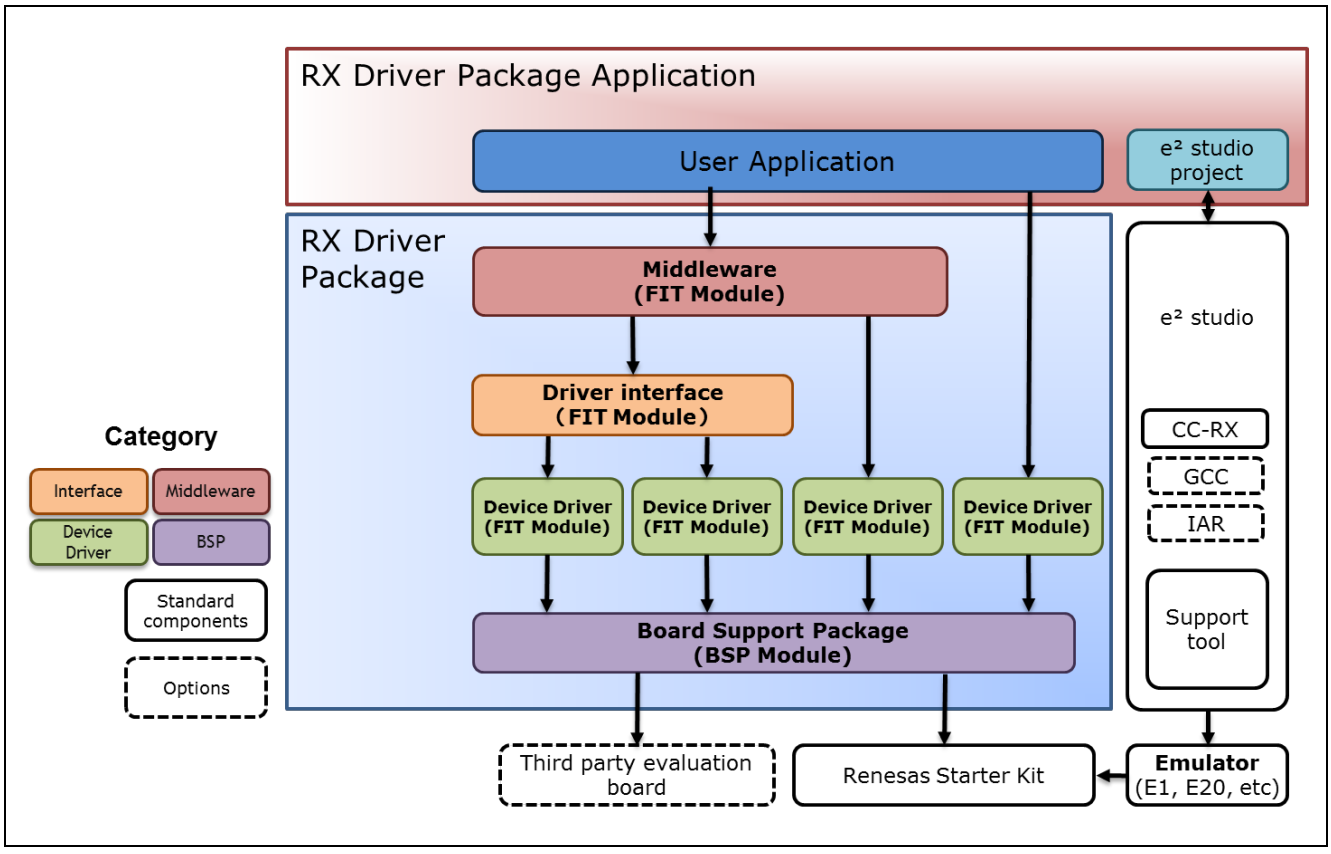

Figure 2-1 System Structure

3. FIT Modules

The table below lists the FIT modules included in this package.

After the release of RX Family RX Driver Package Ver. 1.15 (R01AN4372), many Firmware Integration Technology (FIT) modules have been updated. Differences from Family RX Driver Package Ver. 1.15 are shown in Table 3-1, Table 3-2 and Table 3-3.

The meaning of the terms shown in differences columns are as follows:

"Same"	Includes the same module as previous.
"Updated"	Includes updated modules. Updated contents differ depending on the driver used. Check with the driver's document.
"Added"	Includes the added modules this time.

3.1 Board Support Package (BSP)

Table 3-1 Board Support Package (BSP)

Module	FIT Module Name	Rev	Update Information
Board Support Package (BSP)	r_bsp	3.91	Updated

3.2 Device Driver

Table 3-2 Device Driver

Module	FIT Module Name	Rev	Update Information
Voltage Detection Circuit (LVD)	r_lvd_rx	2.40	Updated
Low Power Consumption (LPC)	r_lpc_rx	1.40	Same
Battery Backup (VBATT)	r_vbatt_rx	1.01	Same
Interrupt Controller (IRQ)	r_irq_rx	2.30	Updated
Data Transfer Controller (DTC)	r_dtc_rx	2.10	Updated
DMA Controller (DMAC)	r_dmaca_rx	1.10	Updated
I/O Ports (GPIO)	r_gpio_rx	2.40	Updated
Multi-Function Pin Controller (MPC)	r_mpc_rx	2.40	Updated
Compare Match Timer (CMT)	r_cmt_rx	3.30	Updated
Compare Match Timer W (CMTW)	r_cmtw_rx	1.31	Same
Real-Time Clock (RTC)	r_rtc_rx	2.72	Same
Low Power Timer (LPT)	r_lpt_rx	1.21	Same
Independent Watchdog Timer (IWDT)	r_iwdt_rx	1.90	Updated
Watchdog Timer (WDT)	r_wdt_rx	1.30	Updated
Serial Communications Interface (SCI: Asynchronous/Clock Synchronous)	r_sci_rx	2.10	Updated
Serial Communications Interface with FIFO (SCI: Asynchronous/Clock Synchronous)	r_scif_rx	1.20	Same
Serial Communications Interface with FIFO (SCIF: Device Driver for Serial Memory Control)	r_scifa_smstr_rx	1.09	Same
Serial Communications Interface (SCI: Simple I^2C Bus)	r_sci_iic_rx	2.30	Updated

I²C Bus Interface (RIIC)	r_riic_rx	2.30	Updated
Serial Peripheral Interface	r_rspi_rx	1.80	Updated
Serial Peripheral Interface (RSPI: Device Driver for Serial Memory Control)	r_rspi_smstr_rx	1.15	Updated
Quad Serial Peripheral Interface (QSPI: Device Driver for Serial Memory Control)	r_qspi_smstr_rx	1.10	Same
USB Basic Firmware	r_usb_basic	1.23	Same
USB Host Mass Storage Class	r_usb_hmsc	1.23	Same
USB Host Communication Device Class	r_usb_hcdc	1.23	Same
USB Host Human Interface Device Class	r_usb_hhid	1.23	Same
USB Peripheral Mass Storage Class	r_usb_pmsc	1.23	Same
USB Peripheral Communications Device Class	r_usb_pcdc	1.23	Same
USB Peripheral Human Interface Device Class	r_usb_phid	1.23	Same
USB Basic Firmware mini	r_usb_basic_mini	1.10	Updated
USB Host Mass Storage Class mini	r_usb_hmsc_mini	1.10	Updated
USB Host Communication Device Class mini	r_usb_hcdc_mini	1.10	Updated
USB Host Human Interface Device Class mini	r_usb_hhid_mini	1.10	Updated
USB Peripheral Mass Storage Class mini	r_usb_pmsc_mini	1.10	Updated
USB Peripheral Communications Device Class mini	r_usb_pcdc_mini	1.10	Updated
USB Peripheral Human Interface Device Class mini	r_usb_phid_mini	1.10	Updated
PTP Module for the Ethernet Controller (EPTPC)	r_ptp_rx	1.14	Same
EPTPC Light Module	r_ptp_light_rx	1.11	Same
Ethernet controller (ETHERC)	r_ether_rx	1.15	Same
CAN Module (CAN)	r_can_rx	2.13	Updated
CAN Module (RSCAN)	r_rscan_rx	1.10	Same
IrDA Interface (IrDA)	r_irda_sci_rx	1.01	Same
Parallel Data Capture Unit (PDC)	r_pdc_rx	2.01	Same
SD Host Interface (SDHI)	r_sdhi_rx	2.01	Same
SD Slave Interface (SDSI)	r_sdsi_rx	2.00	Same
12-Bit A/D Converter (S12AD)	r_s12ad_rx	3.00	Updated
D/A Converter (DAC)	r_dac_rx	3.20	Updated
Flash Memory (On-chip flash memory Programing)	r_flash_rx	3.40	Updated
Sampling Rate Converter (SRC)	r_src_api_rx	1.11	Same
Serial Sound Interface (SSI)	r_ssi_api_rx	1.21	Same
LCD Controller/Driver (LCDC)	r_lcdc_rx	1.00	Same
Graphic LCD Controller (GLCDC)	r_glcdc_rx	1.00	Same
Unique ID Read	r_uid_rx	1.10	Same
Byte Queue Buffer (Data Management)	r_byteq	1.70	Updated
Long Queue Buffer (Data Management)	r_longq	1.70	Updated
Event Link Controller (ELC)	r_elc_rx	1.20	Same

3.3 Middleware/Interface Module

Table 3-3 Middleware/Interface Module

Module	FIT Module Name	Rev	Update Information
TCP/IP M3S-T4-Tiny for Embedding	r_t4_rx	2.07	Same
Interface conversion module for Ethernet Driver and Embedded system M3S-T4-Tiny	r_t4_driver_rx	1.06	Same
System Timer Module	r_sys_time_rx	1.00	Same
SD Mode SD Memory Card Driver	r_sdc_sdmem_rx	2.02	Added
SPI Serial EEPROM Module	r_eeprom_spi	2.34	Same
SPI Serial Flash memory Module	r_flash_spi	2.34	Same
I^2C Bus Interface (RIIC) Module for EEPROM Access	r_eeprom_riic_rx	1.40	Same
Simple I^2C Module for EEPROM Access	r_eeprom_sci_iic_rx	1.30	Same
JPEG Decoder Module	r_jpegd_rx	2.06	Same
JPEG Encoder Module	r_jpege_rx	1.01	Same
Sound playback system and compression system (original ADPCM codec)	r_s2_rx	3.04	Same
M3S-TFAT-Tiny (FAT file system)	r_tfat_rx	3.03	Same
M3S-TFAT-Tiny Memory Driver Interface Module	r_tfat_driver_rx	1.04	Updated

4. Usage

You can easily construct application programs incorporating the RX Driver Package by using the Smart Configurator or FIT Configurator function of e^2 studio.

For instructions on using the RX Driver Package with e^2 studio Smart Configurator and FIT Configurator, CS+, refer to documents under below, which is included in the RX Driver Package.

Table 4-1 related documents for instructions

Item	Related Documents
e^2 studio FIT Configurator	RX Family Adding Firmware Integration Technology Modules to Projects (R01AN1723EU)
e^2 studio Smart Configurator	Renesas e^2 studio Smart Configurator User Guide (R20AN0451ES)
CS+	RX Family Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826EJ)

5. Supplement

5.1 Commercial Version of Middleware and Drivers Supporting FIT

For the information of the latest commercial version (paid) Middleware and Drivers for RX Family, refer to the page of the Middleware and Drivers. https://www.renesas.com/mw

5.2 Sample Program

RX Driver Package is composed of FIT module group in a package, which does not include the sample program for operation confirmation. If the sample program is required, download the FIT module unit package separately*[1]. FIT module unit package has “FITDemos” folder an includes sample program or sample project.

Note 1. Note that some FIT modules may not provide sample program.

5.3 Location of the API Information for FIT Module

For the API information of FIT module embedded in the project, refer to the **doc** folder of each FIT module folder.

5.4 Check the RX Driver Package Downloaded

When successfully downloaded, FIT module is stored in the folder specified in ”FIT Module Folder Path:” described in “4 Usage” (Related Documents)(generally, C:\Renesas\e2_studio\ FITModules).

In “FITModules\Downloaded” folder, ZIP file of the package is stored.

The folder specified in “FIT Module Folder Path:”.

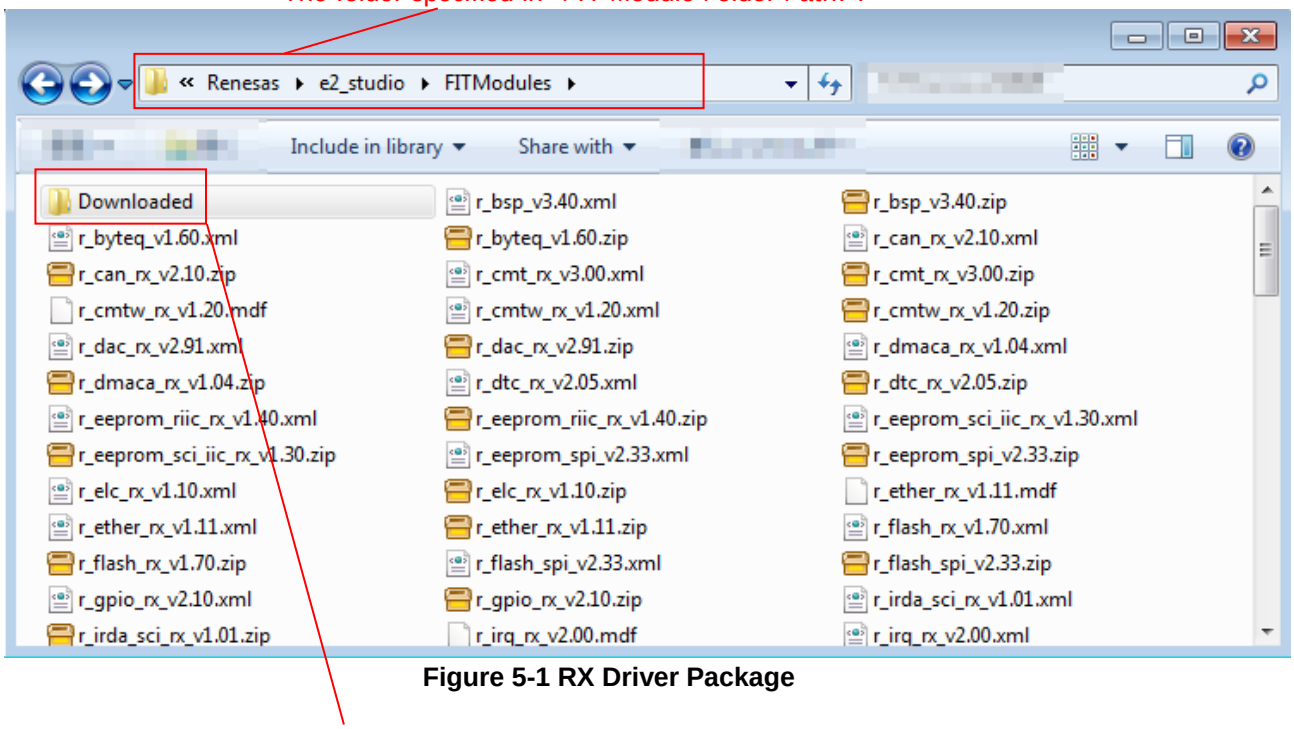

Figure 5-1 RX Driver Package

ZIP file of the package is stored.

（an_r01an****ej****_rx_fit.zip）

Website and Support

Renesas Electronics Website

http://www.renesas.com/

Inquiries

http://www.renesas.com/contact/

Revision History

		Description	
Rev.	**Date**	**Page**	**Summary**
1.16	Nov 20, 2018	-	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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(Rev.4.0-1 November 2017)

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Renesas Electronics Corporation
TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan

Renesas Electronics America Inc.
1001 Murphy Ranch Road, Milpitas, CA 95035, U.S.A.
Tel: +1-408-432-8888, Fax: +1-408-434-5351

Renesas Electronics Canada Limited
9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3
Tel: +1-905-237-2004

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-651-700

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
Room 1709 Quantum Plaza, No.27 ZhichunLu, Haidian District, Beijing, 100191 P. R. China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, 200333 P. R. China
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited
Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2265-6688, Fax: +852 2886-9022

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.
Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics India Pvt. Ltd.
No.777C, 100 Feet Road, HAL 2nd Stage, Indiranagar, Bangalore 560 038, India
Tel: +91-80-67208700, Fax: +91-80-67208777

Renesas Electronics Korea Co., Ltd.
17F, KAMCO Yangjae Tower, 262, Gangnam-daero, Gangnam-gu, Seoul, 06265 Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5338

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